



Flash Memory Summit

XFMEXPRESST™, A New Replaceable SSD Form Factor

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A Reminder Reveal

The XFMEXPRESS™ device form factor has:

- Surface area of 14 mm x 18 mm
- Thickness of 1.4 mm



PCIe® Lanes 0,1

PCIe® Lanes 2, 3

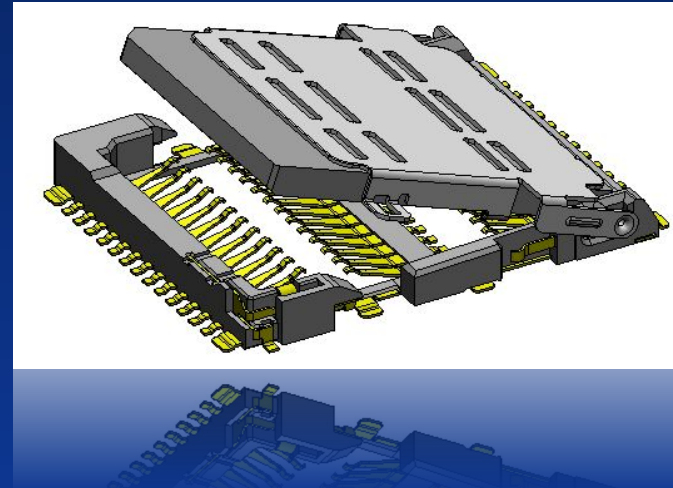
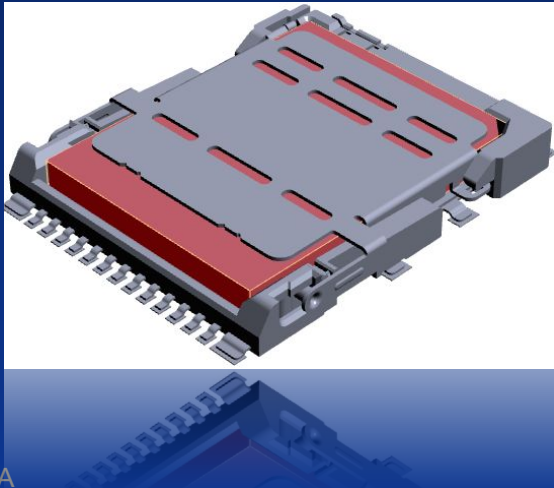
Power & PCIe®
Sideband Signals



The Other Half

The first XFMEXPRESS™ connector has:

- Surface area of 17.8 mm × 22.2 mm
- Thickness of 2.2 mm





Why one more form factor?

There are the compromises of current SSD client products for ultra-mobile and embedded applications:

Large footprint and height limitation (e.g., M.2 2230),

vs.

Not very flexible or serviceable (e.g., BGA 1620)



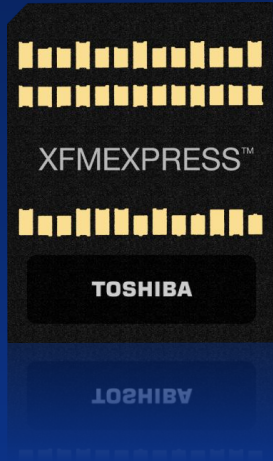
What does XFMEXPRESS™ offer?

XFMEXPRESS™ offers the combination of:

- Serviceability
- A no-compromise balance between a small form factor and support of SSD-class components (e.g., current and future 3D flash)
- Real I/F scalability and the thermal interface to support it
- SSD-class capacity & performance



Designed for Ultra-Mobile & Embedded Use Cases



- XFMEXPRESS™ is a new memory device form factor developed by Toshiba Memory as a joint effort between SSD and Memory teams within Toshiba Memory
- No-compromise embedded & removable NVMe™ storage device
- Optimized mounting volume for host designers



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Designed for Ultra Mobile

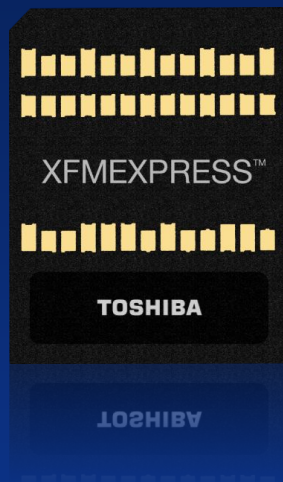
PCIe[®]/NVMe[™] interfaces build today's mainstream client SSD

- PCIe[®] 3.0 Specification
 - x2 and x4 Lane
 - Gen 3, 8 GT/s
 - Design goal for Gen 4, 16 GT/s
- NVMe[™] 1.3 Specification





Capacity and Performance



- Terabyte capacity capable
- Theoretical speeds of up to 4 GB/s on x4 lanes (PCIe[®] Gen 3.0) and up to 8 GB/s on x4 lanes (PCIe[®] Gen 4.0)
- Support for up to 5 watts with 'TIM' thermal treatments

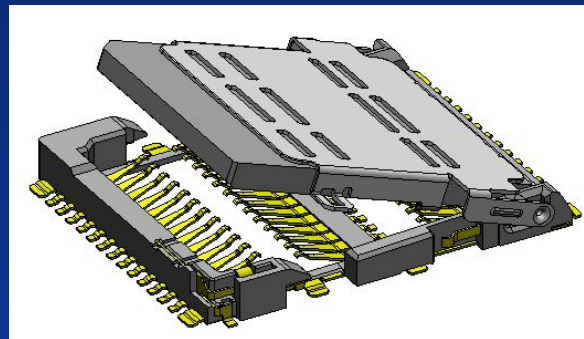
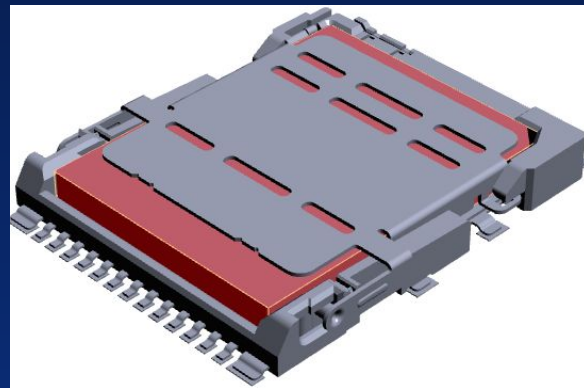


Designed for Ultra-Mobile

A new choice for embedded memory & removable storage/memory devices

A connector designed for:

- Easy replacement
- Minimal real-estate (3D)
- Heat transfer mechanisms optimizable for system target





Target Markets





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XFMEXPRESS™ Standardization

Planning in process for an open standard

Please stay tuned...



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THANK YOU!

Please visit Toshiba Memory
Booth #307

For more information:

<https://business.toshiba-memory.com/en-jp/product/memory/xfmexpress.html>